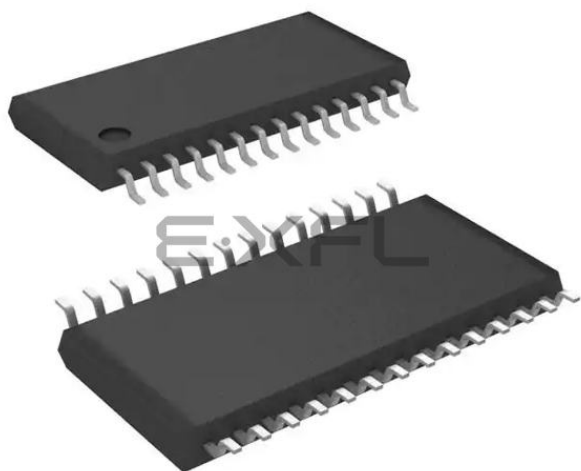




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Details

Product Status	Obsolete
Core Processor	ARM® Cortex®-M0
Core Size	32-Bit Single-Core
Speed	32MHz
Connectivity	I ² C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, I ² S, POR, PWM, WDT
Number of I/O	20
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 14x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	28-TSSOP (0.173", 4.40mm Width)
Supplier Device Package	PG-TSSOP-28-16
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/xmc1202t028x0016aaxuma1

XMC1200

Microcontroller Series
for Industrial Applications

XMC1000 Family

ARM[®] Cortex[™]-M0
32-bit processor core

Data Sheet

V1.4 2014-05

Microcontrollers

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About this Document

This Data Sheet is addressed to embedded hardware and software developers. It provides the reader with detailed descriptions about the ordering designations, available features, electrical and physical characteristics of the XMC1200 series devices.

The document describes the characteristics of a superset of the XMC1200 series devices. For simplicity, the various device types are referred to by the collective term XMC1200 throughout this document.

XMC1000 Family User Documentation

The set of user documentation includes:

- **Reference Manual**
 - describes the functionality of the superset of devices.
- **Data Sheets**
 - list the complete ordering designations, available features and electrical characteristics of derivative devices.
- **Errata Sheets**
 - list deviations from the specifications given in the related Reference Manual or Data Sheets. Errata Sheets are provided for the superset of devices.

Attention: Please consult all parts of the documentation set to attain consolidated knowledge about your device.

Application related guidance is provided by **Users Guides** and **Application Notes**.

Please refer to <http://www.infineon.com/xmc1000> to get access to the latest versions of those documents.

Summary of Features
Table 1 Synopsis of XMC1200 Device Types (cont'd)

Derivative	Package	Flash Kbytes	SRAM Kbytes
XMC1200-T038F0200	PG-TSSOP-38-9	200	16
XMC1202-T028X0016	PG-TSSOP-28-16	16	16
XMC1202-T028X0032	PG-TSSOP-28-16	32	16
XMC1202-T016X0016	PG-TSSOP-16-8	16	16
XMC1202-T016X0032	PG-TSSOP-16-8	32	16
XMC1202-Q024X0016	PG-VQFN-24-19	16	16
XMC1202-Q024X0032	PG-VQFN-24-19	32	16
XMC1201-Q040F0016	PG-VQFN-40-13	16	16
XMC1201-Q040F0032	PG-VQFN-40-13	32	16
XMC1201-Q040F0064	PG-VQFN-40-13	64	16
XMC1201-Q040F0128	PG-VQFN-40-13	128	16
XMC1201-Q040F0200	PG-VQFN-40-13	200	16
XMC1202-Q040X0016	PG-VQFN-40-13	16	16
XMC1202-Q040X0032	PG-VQFN-40-13	32	16

1.3 Device Type Features

The following table lists the available features per device type.

Table 2 Features of XMC1200 Device Types¹⁾

Derivative	ADC channel	ACMP	BCCU	LEDTS
XMC1200-T038	16	3	1	2
XMC1201-T038	16	-	-	2
XMC1202-T028	14	3	1	-
XMC1202-T016	11	2	1	-
XMC1202-Q024	13	3	1	-
XMC1201-Q040	16	-	-	2
XMC1202-Q040	16	3	1	-

1) Features that are not included in this table are available in all the derivatives

Summary of Features

Table 4 XMC1200 Chip Identification Number (cont'd)

Derivative	Value	Marking
XMC1202-T016X0016	00012033 01CF00FF 00001FF7 00008000 00000B00 00001000 00005000 101ED083 _H	AA
XMC1202-T016X0032	00012033 01CF00FF 00001FF7 00008000 00000B00 00001000 00009000 101ED083 _H	AA
XMC1202-Q024X0016	00012063 01CF00FF 00001FF7 00008000 00000B00 00001000 00005000 101ED083 _H	AA
XMC1202-Q024X0032	00012063 01CF00FF 00001FF7 00008000 00000B00 00001000 00009000 101ED083 _H	AA
XMC1201-Q040F0016	00012042 01CF00FF 00001FF7 00006000 00000B00 00001000 00005000 101ED083 _H	AA
XMC1201-Q040F0032	00012042 01CF00FF 00001FF7 00006000 00000B00 00001000 00009000 101ED083 _H	AA
XMC1201-Q040F0064	00012042 01CF00FF 00001FF7 00006000 00000B00 00001000 00011000 101ED083 _H	AA
XMC1201-Q040F0128	00012042 01CF00FF 00001FF7 00006000 00000B00 00001000 00021000 101ED083 _H	AA
XMC1201-Q040F0200	00012042 01CF00FF 00001FF7 00006000 00000B00 00001000 00033000 101ED083 _H	AA
XMC1202-Q040X0016	00012043 01CF00FF 00001FF7 00008000 00000B00 00001000 00005000 101ED083 _H	AA
XMC1202-Q040X0032	00012043 01CF00FF 00001FF7 00008000 00000B00 00001000 00009000 101ED083 _H	AA

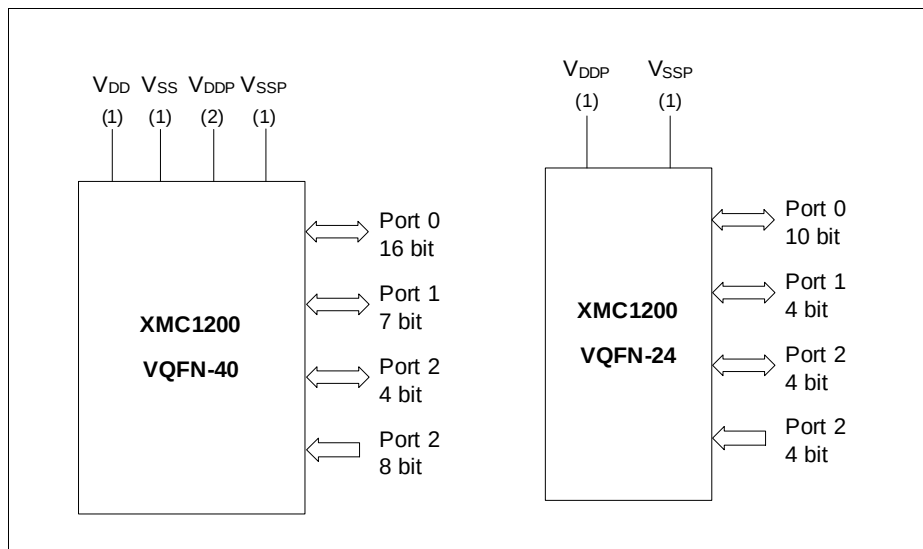


Figure 3 XMC1200 Logic Symbol for VQFN-24 and VQFN-40

2.2 Pin Configuration and Definition

The following figures summarize all pins, showing their locations on the different packages.

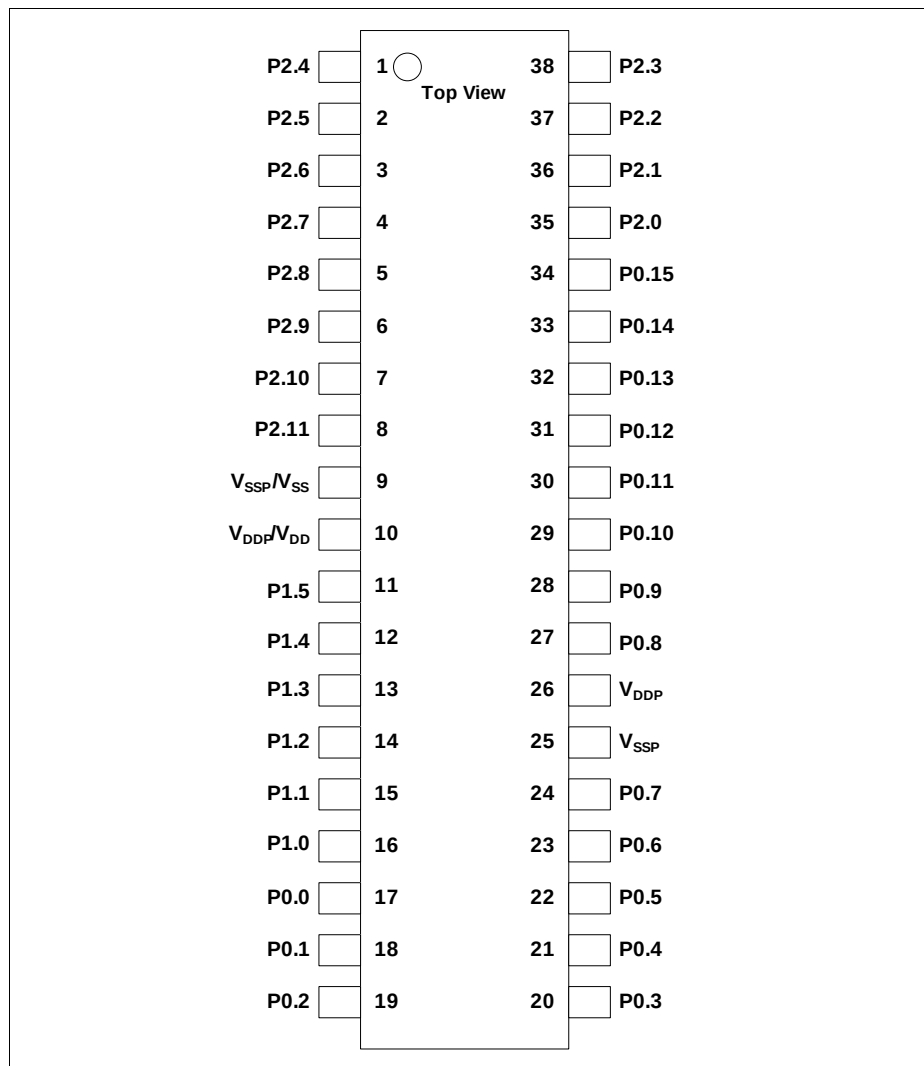


Figure 4 XMC1200 PG-TSSOP-38 Pin Configuration (top view)

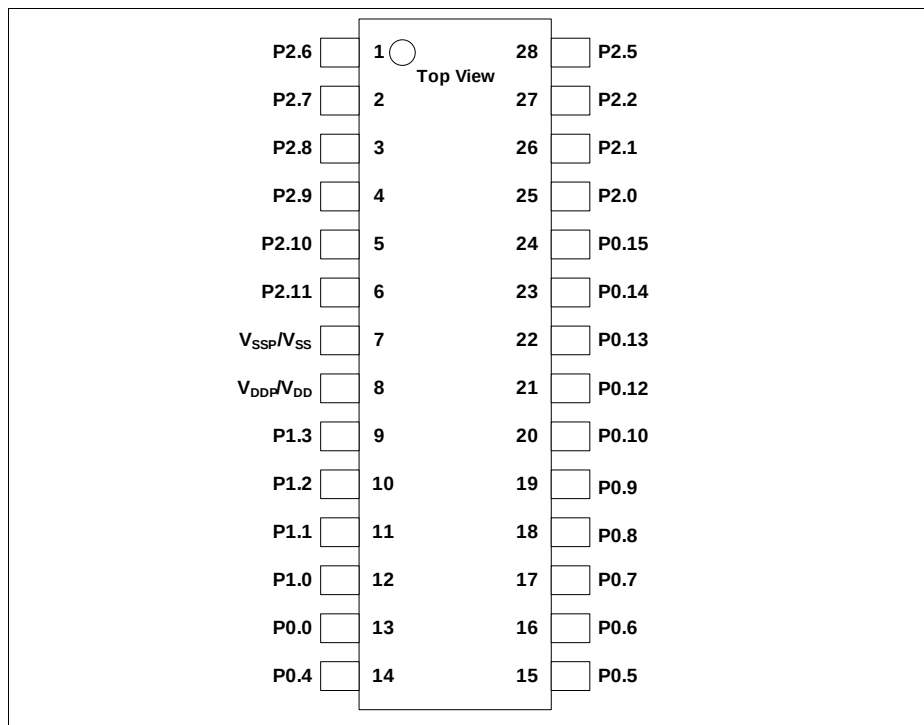


Figure 5 XMC1200 PG-TSSOP-28 Pin Configuration (top view)

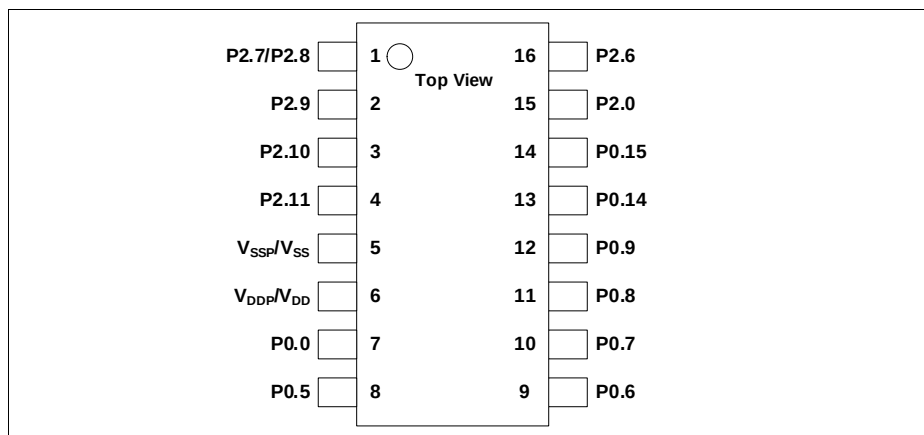


Figure 6 XMC1200 PG-TSSOP-16 Pin Configuration (top view)

Table 8 Port I/O Functions

Function	Outputs								Inputs							
	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7	HWO0	HWO1	HWI0	HWI1	Input	Input	Input	Input	Input
P0.0	ERU0. PDOUT0	LEDTS0. LINE7	ERU0. GOUT0	CCU40. OUT0		USIC0_CH0. SELO0	USIC0_CH1. SELO0	LEDTS0. EXTENDED7		LEDTS0. TSIN7	LEDTS0. TSIN7	BCCU0. TRAPINB	CCU40.IN0C		USIC0_CH0. DX2A	USIC0_CH1. DX2A
P0.1	ERU0. PDOUT1	LEDTS0. LINE6	ERU0. GOUT1	CCU40. OUT1		BCCU0. OUT8	SCU. VDROP	LEDTS0. EXTENDED6		LEDTS0. TSIN6	LEDTS0. TSIN6		CCU40.IN1C			
P0.2	ERU0. PDOUT2	LEDTS0. LINE5	ERU0. GOUT2	CCU40. OUT2		VADC0. EMUX02		LEDTS0. EXTENDED5		LEDTS0. TSIN5	LEDTS0. TSIN5		CCU40.IN2C			
P0.3	ERU0. PDOUT3	LEDTS0. LINE4	ERU0. GOUT3	CCU40. OUT3		VADC0. EMUX01		LEDTS0. EXTENDED4		LEDTS0. TSIN4	LEDTS0. TSIN4		CCU40.IN3C			
P0.4	BCCU0. OUT0	LEDTS0. LINE3	LEDTS0. COL3	CCU40. OUT1		VADC0. EMUX00	WWDT. SERVICE_O UT	LEDTS0. EXTENDED3		LEDTS0. TSIN3	LEDTS0. TSIN3					
P0.5	BCCU0. OUT1	LEDTS0. LINE2	LEDTS0. COL2	CCU40. OUT0		ACMP2. OUT		LEDTS0. EXTENDED2		LEDTS0. TSIN2	LEDTS0. TSIN2					
P0.6	BCCU0. OUT2	LEDTS0. LINE1	LEDTS0. COL1	CCU40. OUT0		USIC0_CH1. MCLKOUT	USIC0_CH1. DOU0	LEDTS0. EXTENDED1		LEDTS0. TSIN1	LEDTS0. TSIN1		CCU40.IN0B		USIC0_CH1. DX0C	
P0.7	BCCU0. OUT3	LEDTS0. LINE0	LEDTS0. COL0	CCU40. OUT1		USIC0_CH0. SCLKOUT	USIC0_CH1. DOU0	LEDTS0. EXTENDED0		LEDTS0. TSIN0	LEDTS0. TSIN0		CCU40.IN1B		USIC0_CH0. DX1C	USIC0_CH1. DX0D
P0.8	BCCU0. OUT4	LEDTS1. LINE0	LEDTS0. COLA	CCU40. OUT2		USIC0_CH0. SCLKOUT	USIC0_CH1. SCLKOUT	LEDTS1. EXTENDED0		LEDTS1. TSIN0	LEDTS1. TSIN0		CCU40.IN2B		USIC0_CH0. DX1B	USIC0_CH1. DX1B
P0.9	BCCU0. OUT5	LEDTS1. LINE1	LEDTS0. COL6	CCU40. OUT3		USIC0_CH0. SELO0	USIC0_CH1. SELO0	LEDTS1. EXTENDED1		LEDTS1. TSIN1	LEDTS1. TSIN1		CCU40.IN3B		USIC0_CH0. DX2B	USIC0_CH1. DX2B
P0.10	BCCU0. OUT6	LEDTS1. LINE2	LEDTS0. COL5	ACMP0. OUT		USIC0_CH0. SELO1	USIC0_CH1. SELO1	LEDTS1. EXTENDED2		LEDTS1. TSIN2	LEDTS1. TSIN2				USIC0_CH0. DX2C	USIC0_CH1. DX2C
P0.11	BCCU0. OUT7	LEDTS1. LINE3	LEDTS0. COL4	USIC0_CH0. MCLKOUT		USIC0_CH0. SELO2	USIC0_CH1. SELO2	LEDTS1. EXTENDED3		LEDTS1. TSIN3	LEDTS1. TSIN3				USIC0_CH0. DX2D	USIC0_CH1. DX2D
P0.12	BCCU0. OUT6	LEDTS1. LINE4	LEDTS0. COL3	LEDTS1. COL3		USIC0_CH0. SELO3		LEDTS1. EXTENDED4		LEDTS1. TSIN4	LEDTS1. TSIN4	BCCU0. TRAPINA	CCU40.IN0A	CCU40.IN1A	CCU40.IN2A	CCU40.IN3A
P0.13	WWDT. SERVICE_O UT	LEDTS1. LINE5	LEDTS0. COL2	LEDTS1. COL2		USIC0_CH0. SELO4		LEDTS1. EXTENDED5		LEDTS1. TSIN5	LEDTS1. TSIN5				USIC0_CH0. DX2F	
P0.14	BCCU0. OUT7	LEDTS1. LINE6	LEDTS0. COL1	LEDTS1. COL1		USIC0_CH0. DOU0	USIC0_CH0. SCLKOUT	LEDTS1. EXTENDED6		LEDTS1. TSIN6	LEDTS1. TSIN6				USIC0_CH0. DX0A	USIC0_CH0. DX1A
P0.15	BCCU0. OUT8	LEDTS1. LINE7	LEDTS0. COL0	LEDTS1. COL0		USIC0_CH0. DOU0	USIC0_CH1. MCLKOUT	LEDTS1. EXTENDED7		LEDTS1. TSIN7	LEDTS1. TSIN7				USIC0_CH0. DX0B	
P1.0	BCCU0. OUT0	CCU40. OUT0	LEDTS0. COL0	LEDTS1. COLA		ACMP1. OUT	USIC0_CH0. DOU0		USIC0_CH0. DOU0		USIC0_CH0. HWIN0				USIC0_CH0. DX0C	
P1.1	VADC0. EMUX00	CCU40. OUT1	LEDTS0. COL1	LEDTS1. COL0		USIC0_CH0. DOU0	USIC0_CH1. SELO0		USIC0_CH0. DOU01		USIC0_CH0. HWIN1				USIC0_CH0. DX0D	USIC0_CH0. DX1D
P1.2	VADC0. EMUX01	CCU40. OUT2	LEDTS0. COL2	LEDTS1. COL1		ACMP2. OUT	USIC0_CH1. DOU0		USIC0_CH0. DOU02		USIC0_CH0. HWIN2				USIC0_CH1. DX0B	
P1.3	VADC0. EMUX02	CCU40. OUT3	LEDTS0. COL3	LEDTS1. COL2		USIC0_CH1. SCLKOUT	USIC0_CH1. DOU0		USIC0_CH0. DOU03		USIC0_CH0. HWIN3				USIC0_CH1. DX0A	USIC0_CH1. DX1A
P1.4	VADC0. EMUX10	USIC0_CH1. SCLKOUT	LEDTS0. COL4	LEDTS1. COL3		USIC0_CH0. SELO0	USIC0_CH1. SELO1								USIC0_CH0. DX5E	USIC0_CH1. DX5E
P1.5	VADC0. EMUX11	USIC0_CH0. DOU0	LEDTS0. COLA	BCCU0. OUT1		USIC0_CH0. SELO1	USIC0_CH1. SELO2								USIC0_CH1. DX5F	

3 Electrical Parameter

This section provides the electrical parameter which are implementation-specific for the XMC1200.

3.1 General Parameters

3.1.1 Parameter Interpretation

The parameters listed in this section represent partly the characteristics of the XMC1200 and partly its requirements on the system. To aid interpreting the parameters easily when evaluating them for a design, they are indicated by the abbreviations in the "Symbol" column:

- **CC**
Such parameters indicate **C**ontroller **C**haracteristics, which are distinctive feature of the XMC1200 and must be regarded for a system design.
- **SR**
Such parameters indicate **S**ystem **R**equirements, which must be provided by the application system in which the XMC1200 is designed in.

Table 11 Input/Output Characteristics (Operating Conditions apply) (cont'd)

Parameter	Symbol		Limit Values		Unit	Test Conditions
			Min.	Max.		
Maximum current into V_{DDP} (TSSOP28/16, VQFN24)	I_{MVDD1}	SR	–	130	mA	³⁾
Maximum current into V_{DDP} (TSSOP38, VQFN40)	I_{MVDD2}	SR	–	260	mA	³⁾
Maximum current out of V_{SS} (TSSOP28/16, VQFN24)	I_{MVSS1}	SR	–	130	mA	³⁾
Maximum current out of V_{SS} (TSSOP38, VQFN40)	I_{MVSS2}	SR	–	260	mA	³⁾

- 1) Not subject to production test, verified by design/characterization. Hysteresis is implemented to avoid meta stable states and switching due to internal ground bounce. It cannot be guaranteed that it suppresses switching due to external system noise.
- 2) An additional error current (I_{INJ}) will flow if an overload current flows through an adjacent pin.
- 3) Not subject to production test, verified by design/characterization.
- 4) Not subject to production test, verified by design/characterization. However, for applications with strict low power-down current requirements, it is mandatory that no active voltage source is supplied at any GPIO pin when V_{DDP} is powered off.

Electrical Parameter
Table 12 ADC Characteristics (Operating Conditions apply) (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Gain settings	G_{IN} CC	1			–	GNCTRxz.GAINy = 00 _B (unity gain)
		3			–	GNCTRxz.GAINy = 01 _B (gain g1)
		6			–	GNCTRxz.GAINy = 10 _B (gain g2)
		12			–	GNCTRxz.GAINy = 11 _B (gain g3)
Sample Time	t_{sample} CC	3	–	–	1 / f_{ADC}	$V_{DDP} = 5.0$ V
		3	–	–	1 / f_{ADC}	$V_{DDP} = 3.3$ V
		30	–	–	1 / f_{ADC}	$V_{DDP} = 1.8$ V
Sigma delta loop hold time	t_{SD_hold} CC	20	–	–	μs	Residual charge stored in an active sigma delta loop remains available
Conversion time in fast compare mode	t_{CF} CC	9			1 / f_{ADC}	²⁾
Conversion time in 12-bit mode	t_{C12} CC	20			1 / f_{ADC}	²⁾
Maximum sample rate in 12-bit mode ³⁾	f_{C12} CC	–	–	$f_{ADC} / 42.5$	–	1 sample pending
		–	–	$f_{ADC} / 62.5$	–	2 samples pending
Conversion time in 10-bit mode	t_{C10} CC	18			1 / f_{ADC}	²⁾
Maximum sample rate in 10-bit mode ³⁾	f_{C10} CC	–	–	$f_{ADC} / 40.5$	–	1 sample pending
		–	–	$f_{ADC} / 58.5$	–	2 samples pending
Conversion time in 8-bit mode	t_{C8} CC	16			1 / f_{ADC}	²⁾

3.2.3 Out of Range Comparator (ORC) Characteristics

The Out-of-Range Comparator (ORC) triggers on analog input voltages (V_{AIN}) above the V_{DDP} on selected input pins (ORCx.AIN) and generates a service request trigger (ORCx.OUT).

Note: These parameters are not subject to production test, but verified by design and/or characterization.

Table 13 Out of Range Comparator (ORC) Characteristics (Operating Conditions apply; $V_{DDP} = 3.0\text{ V} - 5.5\text{ V}$)

Parameter	Symbol		Values			Unit	Note / Test Condition
			Min.	Typ.	Max.		
DC Switching Level	V_{ODC}	CC	60	–	120	mV	$V_{AIN} \geq V_{DDP} + V_{ODC}$
Hysteresis	V_{OHYS}	CC	25	–	V_{ODC}	mV	
Always detected Overvoltage Pulse	t_{OPDD}	CC	103	–	–	ns	$V_{AIN} \geq V_{DDP} + 150\text{ mV}$
			88	–	–	ns	$V_{AIN} \geq V_{DDP} + 350\text{ mV}$
Never detected Overvoltage Pulse	t_{OPDN}	CC	–	–	21	ns	$V_{AIN} \geq V_{DDP} + 150\text{ mV}$
			–	–	11	ns	$V_{AIN} \geq V_{DDP} + 350\text{ mV}$
Detection Delay	t_{ODD}	CC	39	–	132	ns	$V_{AIN} \geq V_{DDP} + 150\text{ mV}$
			31	–	121	ns	$V_{AIN} \geq V_{DDP} + 350\text{ mV}$
Release Delay	t_{ORD}	CC	44	–	240	ns	$V_{AIN} \leq V_{DDP}$; $V_{DDP} = 5\text{ V}$
			57	–	340	ns	$V_{AIN} \leq V_{DDP}$; $V_{DDP} = 3.3\text{ V}$
Enable Delay	t_{OED}	CC	–	–	300	ns	ORCCTRL.ENORCx = 1

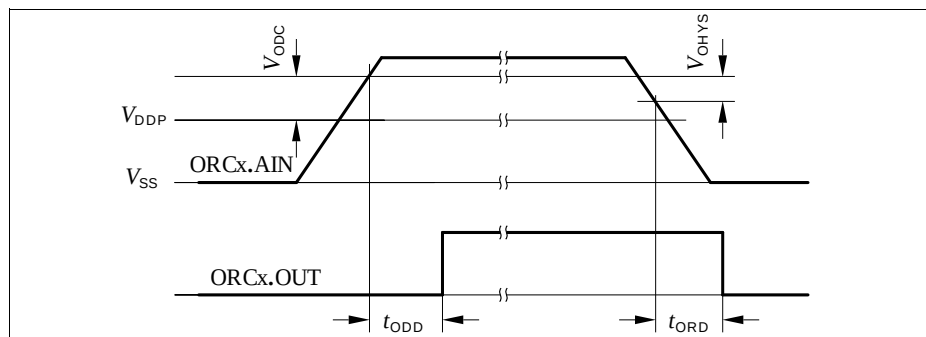


Figure 10 ORCx.OUT Trigger Generation

3.2.5 Temperature Sensor Characteristics

Table 15 Temperature Sensor Characteristics¹⁾

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Measurement time	t_M CC	–	–	10	ms	
Temperature sensor range	T_{SR} SR	-40	–	115	°C	
Sensor Accuracy ²⁾	T_{TSAL} CC	–	+/- 20	–	°C	$T_J = -40\text{ °C}$
		–	+/- 12	–	°C	$T_J = -25\text{ °C}$
		-5	–	5	°C	$T_J = 0\text{ °C}$
		-2	–	2	°C	$T_J = 25\text{ °C}$
		-4	–	4	°C	$T_J = 70\text{ °C}$
		-2	–	2	°C	$T_J = 115\text{ °C}$

1) Not subject to production test, verified by design/characterization.

2) The temperature sensor accuracy is independent of the supply voltage.

Table 26 USIC SSC Slave Mode Timing (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Receive data input DX0/DX[5:3] setup time to shift clock receive edge ¹⁾	t_{12} SR	10	–	–	ns	
Data input DX0/DX[5:3] hold time from clock input DX1 receive edge ¹⁾	t_{13} SR	10	–	–	ns	
Data output DOUT[3:0] valid time	t_{14} CC	-	–	80	ns	

1) These input timings are valid for asynchronous input signal handling of slave select input, shift clock input, and receive data input (bits DXnCR.DSEN = 0).

3.3.7.2 Inter-IC (IIC) Interface Timing

The following parameters are applicable for a USIC channel operated in IIC mode.

Note: Operating Conditions apply.

Table 27 USIC IIC Standard Mode Timing¹⁾

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Fall time of both SDA and SCL	t_1 CC/SR	-	-	300	ns	
Rise time of both SDA and SCL	t_2 CC/SR	-	-	1000	ns	
Data hold time	t_3 CC/SR	0	-	-	μs	
Data set-up time	t_4 CC/SR	250	-	-	ns	
LOW period of SCL clock	t_5 CC/SR	4.7	-	-	μs	
HIGH period of SCL clock	t_6 CC/SR	4.0	-	-	μs	
Hold time for (repeated) START condition	t_7 CC/SR	4.0	-	-	μs	
Set-up time for repeated START condition	t_8 CC/SR	4.7	-	-	μs	
Set-up time for STOP condition	t_9 CC/SR	4.0	-	-	μs	
Bus free time between a STOP and START condition	t_{10} CC/SR	4.7	-	-	μs	
Capacitive load for each bus line	C_b SR	-	-	400	pF	

1) Due to the wired-AND configuration of an IIC bus system, the port drivers of the SCL and SDA signal lines need to operate in open-drain mode. The high level on these lines must be held by an external pull-up device, approximately 10 kOhm for operation at 100 kbit/s, approximately 2 kOhm for operation at 400 kbit/s.

Table 28 USIC IIC Fast Mode Timing ¹⁾

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Fall time of both SDA and SCL	t_1 CC/SR	20 + 0.1 * C_b ²⁾	-	300	ns	
Rise time of both SDA and SCL	t_2 CC/SR	20 + 0.1 * C_b	-	300	ns	
Data hold time	t_3 CC/SR	0	-	-	μs	
Data set-up time	t_4 CC/SR	100	-	-	ns	
LOW period of SCL clock	t_5 CC/SR	1.3	-	-	μs	
HIGH period of SCL clock	t_6 CC/SR	0.6	-	-	μs	
Hold time for (repeated) START condition	t_7 CC/SR	0.6	-	-	μs	
Set-up time for repeated START condition	t_8 CC/SR	0.6	-	-	μs	
Set-up time for STOP condition	t_9 CC/SR	0.6	-	-	μs	
Bus free time between a STOP and START condition	t_{10} CC/SR	1.3	-	-	μs	
Capacitive load for each bus line	C_b SR	-	-	400	pF	

1) Due to the wired-AND configuration of an IIC bus system, the port drivers of the SCL and SDA signal lines need to operate in open-drain mode. The high level on these lines must be held by an external pull-up device, approximately 10 kOhm for operation at 100 kbit/s, approximately 2 kOhm for operation at 400 kbit/s.

2) C_b refers to the total capacitance of one bus line in pF.

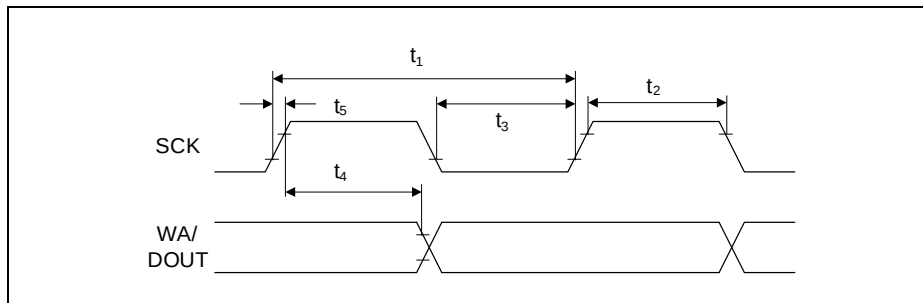


Figure 19 USIC IIS Master Transmitter Timing

Table 30 USIC IIS Slave Receiver Timing

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Clock period	t_6 SR	$4/f_{MCLK}$	-	-	ns	
Clock HIGH	t_7 SR	$0.35 \times t_{6min}$	-	-	ns	
Clock Low	t_8 SR	$0.35 \times t_{6min}$	-	-	ns	
Set-up time	t_9 SR	$0.2 \times t_{6min}$	-	-	ns	
Hold time	t_{10} SR	10	-	-	ns	

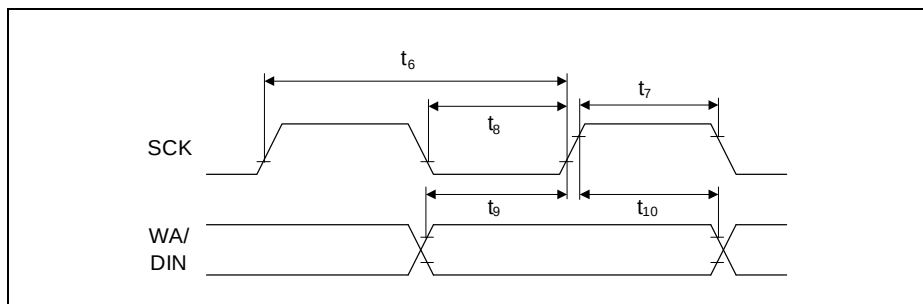


Figure 20 USIC IIS Slave Receiver Timing

4 Package and Reliability

The XMC1200 is a member of the XMC1000 Derivatives of microcontrollers. It is also compatible to a certain extent with members of similar families or subfamilies.

Each package is optimized for the device it houses. Therefore, there may be slight differences between packages of the same pin-count but for different device types. In particular, the size of the exposed die pad may vary.

If different device types are considered or planned for an application, it must be ensured that the board layout fits all packages under consideration.

4.1 Package Parameters

Table 31 provides the thermal characteristics of the packages used in XMC1200.

Table 31 Thermal Characteristics of the Packages

Parameter	Symbol	Limit Values		Unit	Package Types
		Min.	Max.		
Exposed Die Pad Dimensions	Ex × Ey CC	-	2.7 × 2.7	mm	PG-VQFN-24-19
		-	3.7 × 3.7	mm	PG-VQFN-40-13
Thermal resistance Junction-Ambient	$R_{\Theta JA}$ CC	-	104.6	K/W	PG-TSSOP-16-8 ¹⁾
		-	83.2	K/W	PG-TSSOP-28-16 ¹⁾
		-	70.3	K/W	PG-TSSOP-38-9 ¹⁾
		-	46.0	K/W	PG-VQFN-24-19 ¹⁾
		-	38.4	K/W	PG-VQFN-40-13 ¹⁾

1) Device mounted on a 4-layer JEDEC board (JESD 51-5); exposed pad soldered.

Note: For electrical reasons, it is required to connect the exposed pad to the board ground V_{SSP} , independent of EMC and thermal requirements.

4.1.1 Thermal Considerations

When operating the XMC1200 in a system, the total heat generated in the chip must be dissipated to the ambient environment to prevent overheating and the resulting thermal damage.

The maximum heat that can be dissipated depends on the package and its integration into the target board. The "Thermal resistance $R_{\Theta JA}$ " quantifies these parameters. The power dissipation must be limited so that the average junction temperature does not exceed 115 °C.

5 Quality Declaration

Table 32 shows the characteristics of the quality parameters in the XMC1200.

Table 32 Quality Parameters

Parameter	Symbol	Limit Values		Unit	Notes
		Min.	Max.		
ESD susceptibility according to Human Body Model (HBM)	V_{HBM} SR	-	2000	V	Conforming to EIA/JESD22-A114-B
ESD susceptibility according to Charged Device Model (CDM) pins	V_{CDM} SR	-	500	V	Conforming to JESD22-C101-C
Moisture sensitivity level	MSL CC	-	3	-	JEDEC J-STD-020C